



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2018-06-05
<b>Company Unique ID</b>	NL 008751171B01		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Floriana SAN BIAGIO	<b>Representative Title</b>	AMS MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	DDV1*L791AC6	A	BO2A	2018-06-05
	Amount	UoM	Unit type	ST ECOPACK Grade
	5540	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
Not Applicable	Not Applicable	Not Applicable		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
CHP	10.7x20x4.5	11	flat	
Comment	V1 MULTIWATT 11L SPLIT VERT.; MDF valid for TDA7292			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
-	-			0
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
-	-	0.00		

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	DDV1*L791AC6				5999999.0	1000000.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	14.509	mg	supplier	die	Silicon (Si)	7440-21-3		14.180	mg	977324	2560
				supplier	metallization	Aluminium (Al)	7429-90-5		0.179	mg	12337	32
				supplier	Passivation	Silicon Nitride	12033-89-5		0.062	mg	4273	11
				supplier	Passivation	Silicon Oxide	7631-86-9		0.088	mg	6065	16
Leadframe	M-004 Copper and its alloys	4320.837	mg	supplier	alloy	Copper (Cu)	7440-50-8		4315.219	mg	998700	778920
				supplier	alloy	Iron (Fe)	7439-89-6		1.988	mg	460	359
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		3.630	mg	840	655
				supplier	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	12.191	mg	974968
Soft solder	Solder	12.504	mg	supplier	solder	Silver (Ag)	7440-22-4		0.188	mg	15035	34
				supplier	solder	Tin (Sn)	7440-31-5		0.125	mg	9997	23
				supplier	wire	Copper (Cu)	7440-50-8		0.818	mg	1000000	148
Encapsulation	M-015 Other organic materials	1165.943	mg	supplier	mold compound	Silica, vitreous	60676-86-0		835.981	mg	717000	150899
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		198.210	mg	170000	35778
				supplier	mold compound	Phenol resin	9003-35-4		83.948	mg	72000	15153
				supplier	mold compound	Brominated epoxy resin	40039-93-8		17.489	mg	15000	3157
				supplier	mold compound	Antimony Trioxide	1309-64-4		23.319	mg	20000	4209
				supplier	mold compound	Bismuth	7440-69-9		3.498	mg	3000	631
connections coating	Solder	25.389	mg	supplier	mold compound	Carbon black	1333-86-4		3.498	mg	3000	631
				supplier	solder alloy	Tin (Sn)	7440-31-5		25.389	mg	1000000	4583